

05-11-2001

U.S. DEPARTMENT	OF COMMERCE

	Patent and Trademark Office		
To the Honorable Commissioner of Patents and Trademarks: Please record the amount of Copy thereof.			
 Name of conveying party(ies) Daisuke ISHII 	2. Name and address of receiving party(ies)		
2) Tomonari MURAKAMI	Name: SONY CORPORATION		
Additional name(s) of conveying party(ies) attached No	Internal Address:		
3. Nature of conveyance:	Street Address: 7-35 Kitashinagawa 6-chome Shinagawa-ku		
■ Assignment	City: Tokyo, JAPAN		
☐ Security Agreement ☐ Change of Name	Additional name(s) & address(es) attached ☐ Yes ☒ No		
Other			
Execution Date: 1) March 30, 2001; 2) April 9, 2001			
4. Application number(s) or patent number(s): 29/136,323			
If the document is being filed together with a new application, the	execution date of the application is		
Additional numbers attached No			
 Name and address of party to whom correspondence concerning document should be mailed: 	6. Total number of applications and patents involved: 1		
Name: RADER, FISHMAN & GRAUER	7. Total fee (37 CFR 3.41) \$ 40.00		
Internal Address: Suite 501	□ Enclosed		
	Authorized to be charged to Deposit Account		
Street Address: 1233 20 th Street, NW	8. Deposit account number: 18-0013		
City: Washington, D.C. Zip: 20036	(Attach duplicate copy of this page if paying by deposit account)		
DO NOT USE THIS SPACE			
9. Statement and signature. To the best of my knowledge and belief, the foregoing information document. Eugene G. Byrd Reg. No. 47,361 Name of Person Signing	May 1, 2001 Date Total number of pages comprising cover sheet 1		
20000041 180013 29136323			

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PATENT

REEL: 011774 FRAME: 0605

Docket Number: SDE-1017

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35, Kitashinagawa 6-chome, Shinagawa-ku, Tokyo, JAPAN, (hereinafter referenced as ASSIGNEES) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar, legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of Ten Dollar (\$10.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEES, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEES, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEES or its designee, as ASSIGNEES or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

PATENT REEL: 011774 FRAME: 0606 And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEES will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: 29/136,323 , Filing Date: January 30, 2001.

This assignment executed on the dates indicated below.

Dalauka ISHII	
Name of first inventor	Execution date of U.S. Patent Application
Tokyo, Japan	
Residence of first inventor	
J. 15th.	30. Mr. 200
Signature of first inventor	Date of this assignment
Tomonari MURAKAMI	
Name of second inventor	Execution date of U.S. Patent Application
Tokyo, Japan	
Residence of second inventor	
Jomonary Murahami Signature of second inventor	April. 9. 2001
Signature of second inventor	Date of this assignment

PATENT REEL: 011774 FRAME: 0607

RECORDED: 05/01/2001